In the Claims:

Claim 26 (currently amended) An electronic package comprising:

a first circuitized substrate having at least one conductive aperture therein having an external surface;

a second circuitized substrate having at least one conductive aperture therein having an external surface, said first and second circuitized substrates aligned such that said at least one conductive aperture of said first circuitized substrate is substantially aligned with said at least one conductive aperture of said second circuitized substrate, said at least one conductive aperture of said first circuitized substrate and said at least one conductive aperture of said second circuitized substrate including a conductive metallic layer thereon selected from the group consisting of copper, nickel, gold, chromium, solder and alloys thereof; and

at least one high melt solder alloy member having a melting point greater than about 183° Celsius with said solder member including a first contact portion extending from said external surface of said conductive aperture of said first circuitized substrate, said first contact portion including a cross-sectional configuration that is substantially round, oval or ellipsoidal, and a second contact portion extending substantially within both of said aligned conductive apertures of said first and second circuitized substrates to at least said external surface of said conductive aperture of said second circuitized substrate to secure said circuitized substrates together.

Claim 27 (canceled)

Claim 28 (previously amended) The electronic package of Claim 26 wherein said conductive metallic layer is copper including a protective layer thereon, said protective layer selected from the group consisting of benzotriazole, chlorite, and immersion tin.

Claim 29 (canceled)

Claim 30 (currently amended) The electronic package of Claim 26 ~~29~~ wherein said high melt solder alloy member is comprised of metallic material, said metallic material is selected from the group consisting of tin, lead, gold, silver, antimony, and combinations thereof.

Claim 31 (canceled)

Claim 32 (new) An electronic package comprising:

a first circuitized substrate having at least one conductive aperture therein having an external surface, said first circuitized substrate comprised of material selected from the group consisting of polyimide, polytetrafluoroethylene and epoxy glass cloth;

a second circuitized substrate having at least one conductive aperture therein having an external surface, said second circuitized substrate comprised of material selected from the group consisting of polyimide, polytetrafluoroethylene and epoxy glass cloth, said first and second circuitized substrates aligned such that said at least one conductive aperture of said first circuitized substrate is substantially aligned with said at least one conductive aperture of said second circuitized substrate, said at least one conductive

aperture of said first circuitized substrate and said at least one conductive aperture of said second circuitized substrate including a conductive metallic layer thereon selected from the group consisting of copper, nickel, gold, chromium, solder and alloys thereof; and

at least one solder member including a first contact portion extending from said external surface of said conductive aperture of said first circuitized substrate, said first contact portion including a cross-sectional configuration that is substantially round, oval or ellipsoidal, and a second contact portion extending substantially within both of said aligned conductive apertures of said first and second circuitized substrates to at least said external surface of said conductive aperture of said second circuitized substrate to secure said circuitized substrates together.

Claim 33 (new) An electronic package comprising:

a first circuitized substrate having at least one conductive aperture therein having an external surface;

a second circuitized substrate having at least one conductive aperture therein having an external surface, said first and second circuitized substrates aligned such that said at least one conductive aperture of said first circuitized substrate is substantially aligned with said at least one conductive aperture of said second circuitized substrate, said at least one conductive aperture of said first circuitized substrate and said at least one conductive aperture of said second circuitized substrate including a conductive metallic layer thereon selected from the group consisting of copper, nickel, gold, chromium, solder and alloys thereof; and

at least one solder member including a first contact portion extending from said external surface of said conductive aperture of said first circuitized substrate to form a connection to a printed circuit board, said first contact portion including a cross-sectional configuration that is substantially round, oval or ellipsoidal, and a second contact portion extending substantially within both of said aligned conductive apertures of said first and second circuitized substrates to at least said external surface of said conductive aperture of said second circuitized substrate to secure said circuitized substrates together.